SN54136, SN54LS136, SN74136, SN74LS136
QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES
WITH OPEN-COLLECTOR OUTPUTS

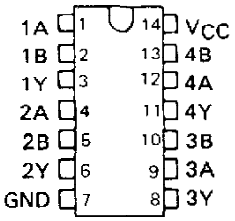
DECEMBER 1972 – REVISED MARCH 1988

FUNCTION TABLE

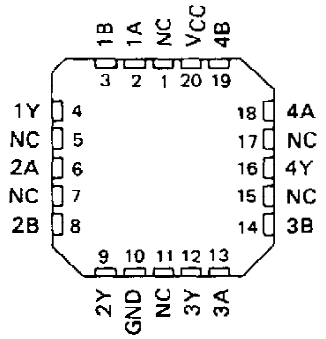
INPUTS		OUTPUT
A	B	Y
L	L	L
L	H	H
H	L	H
H	H	L

H = high level, L = low level

SN54136, SN54LS136 . . . J OR W PACKAGE
SN74136 . . . N PACKAGE
SN74LS136 . . . D OR N PACKAGE
(TOP VIEW)

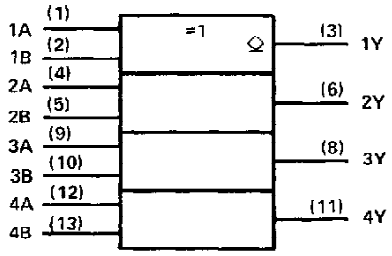


SN54LS136 . . . FK PACKAGE
(TOP VIEW)



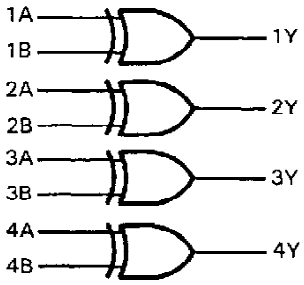
NC – No internal connection

logic symbol†



†This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, N, and W packages.

logic diagram (each gate)

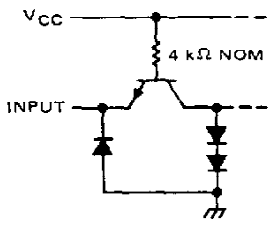


positive logic

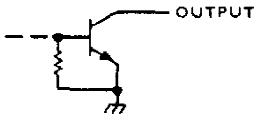
$$Y = A \oplus B = \overline{A} \cdot B + A \cdot \overline{B}$$

schematics of inputs and outputs

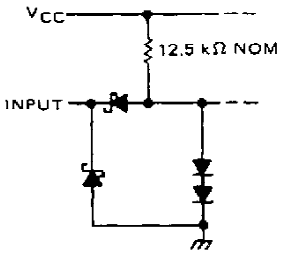
EQUIVALENT OF EACH INPUT OF '136



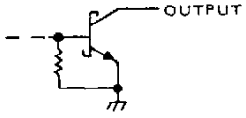
TYPICAL OF ALL OUTPUTS OF '136



EQUIVALENT OF EACH INPUT OF 'LS136



TYPICAL OF ALL OUTPUTS OF 'LS136



Resistor values shown are nominal.

TEXAS INSTRUMENTS
POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 5.5 V
Operating free-air temperature range: SN54136 . . . . . −55°C to 125°C
SN74136 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SN54136			SN74136			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level input voltage, V_{IH}	2			2			V
Low-level input voltage, V_{IL}			0.8			0.8	V
High-level output voltage, V_{OH}			5.5			5.5	V
Low-level output current, I_{OL}			16			16	mA
Operating free-air temperature, T_A	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54136			SN74136			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN, I_I = −8 mA			−1.5			−1.5	V
I_{OH}	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, V_{OH} = 5.5 V						0.25	mA
	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.7 V, V_{OH} = 5.5 V			0.25				
V_{OL}	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OL} = 16 mA		0.2	0.4		0.2	0.4	V
I_I	V_{CC} = MAX, V_I = 5.5 V			1			1	mA
I_{IH}	V_{CC} = MAX, V_I = 2.4 V			40			40	μA
I_{IL}	V_{CC} = MAX, V_I = 0.4 V			−1.6			−1.6	mA
I_{CC}	V_{CC} = MAX, See Note 2		30	43		30	50	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
NOTE 2: I_{CC} is measured with one input of each gate at 4.5 V, the other inputs grounded, and the outputs open.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER¶	FROM (INPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	A or B	Other input low	C_L = 15 pF, R_L = 400 Ω, See Note 3		12	18	ns
t_{PHL}					39	50	
t_{PLH}	A or B	Other input high			14	22	ns
t_{PHL}					42	55	

¶ t_{PLH} propagation delay time, low-to-high-level output
t_{PLH} propagation delay time, high-to-low-level output
NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 7 V
Operating free-air temperature range: SN54LS136 . . . . . −55°C to 125°C
SN74LS136 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SN54LS136			SN74LS136			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output voltage, V_{OH}			5.5			5.5	V
Low-level output current, I_{OL}			4			8	mA
Operating free-air temperature, T_A	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		SN54LS136			SN74LS136			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage			2			2			V
V_{IL}	Low-level input voltage					0.7			0.8	V
V_{IK}	Input clamp voltage	V_{CC} = MIN,	I_I = −18 mA			−1.5			−1.5	V
I_{OH}	High-level output current	V_{CC} = MIN, V_{IL} = V_{IL} max,	V_{IH} = 2 V, V_{OH} = 5.5 V			100			100	μA
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = V_{IL} max	I_{OL} = 4 mA		0.25	0.4		0.25	0.4	V
			I_{OL} = 8 mA					0.35	0.5	
I_I	Input current at maximum input voltage	V_{CC} = MAX,	V_I = 7 V			0.2			0.2	mA
I_{IH}	High-level input current	V_{CC} = MAX,	V_I = 2.7 V			40			40	μA
I_{IL}	Low-level input current	V_{CC} = MAX,	V_I = 0.4 V			−0.8			−0.8	mA
I_{CC}	Supply current	V_{CC} = MAX,	See Note 2		6.1	10		6.1	10	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
NOTE 2: I_{CC} is measured with one input of each gate at 4.5 V, the other inputs grounded, and the outputs open.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER¶	FROM (INPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	A or B	Other input low	C_L = 15 pF, R_L = 2 kΩ, (See Note 3)		18	30	ns
t_{PHL}					18	30	
t_{PLH}	A or B	Other input high			18	30	ns
t_{PHL}					18	30	

¶t_{PLH} propagation delay time, low-to-high-level output
t_{PLH} propagation delay time, high-to-low-level output
NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-9231901MCA	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9231901MC A SNJ54LS136J
SN54LS136J	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS136J
SN54LS136J.A	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS136J
SN74LS136DR	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS136
SN74LS136DR.A	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS136
SN74LS136DR.B	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	-	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS136
SN74LS136N	Active	Production	PDIP (N) | 14	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS136N
SN74LS136N.A	Active	Production	PDIP (N) | 14	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS136N
SN74LS136NE4	Active	Production	PDIP (N) | 14	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS136N
SN74LS136NSR	Active	Production	SOP (NS) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS136
SN74LS136NSR.A	Active	Production	SOP (NS) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS136
SNJ54LS136J	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9231901MC A SNJ54LS136J
SNJ54LS136J.A	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9231901MC A SNJ54LS136J

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54LS136, SN74LS136 :

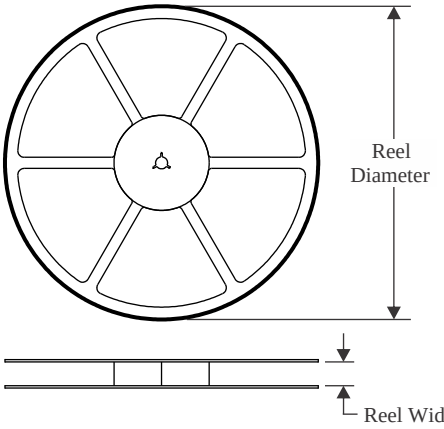
- Catalog : SN74LS136
- Military : SN54LS136

NOTE: Qualified Version Definitions:

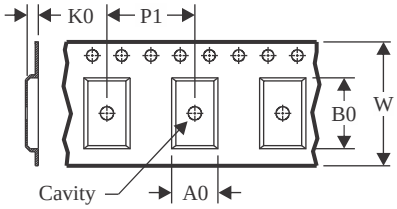
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

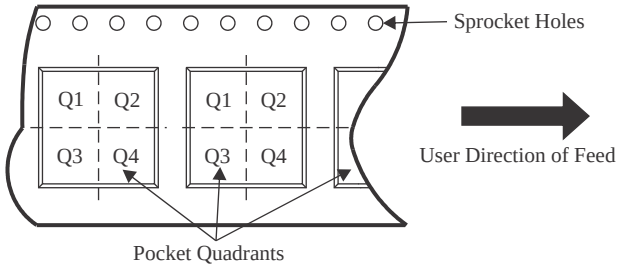


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

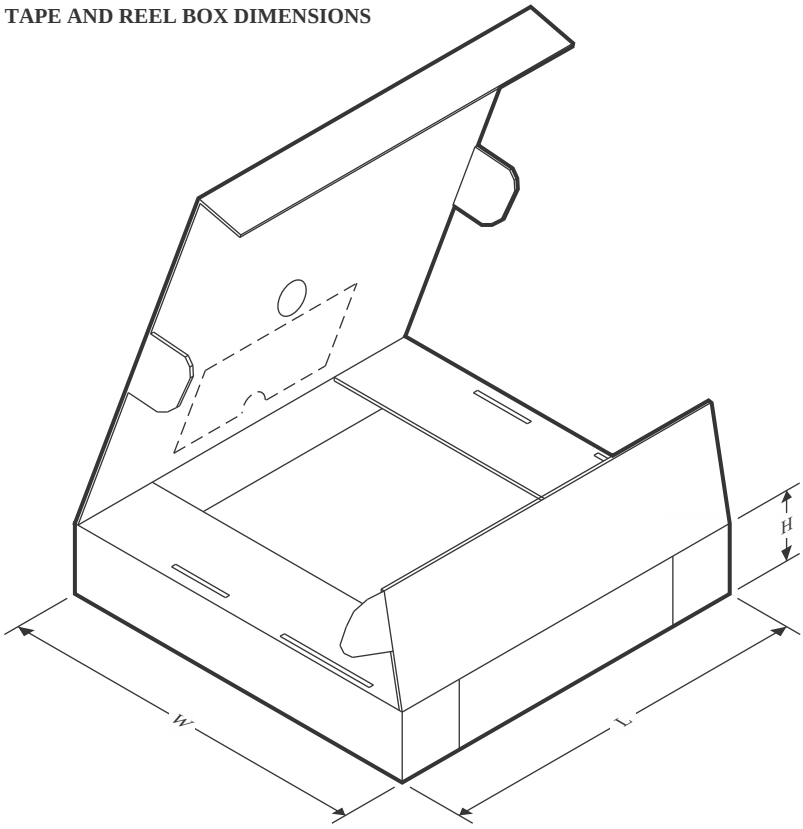
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS136DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS136NSR	SOP	NS	14	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1

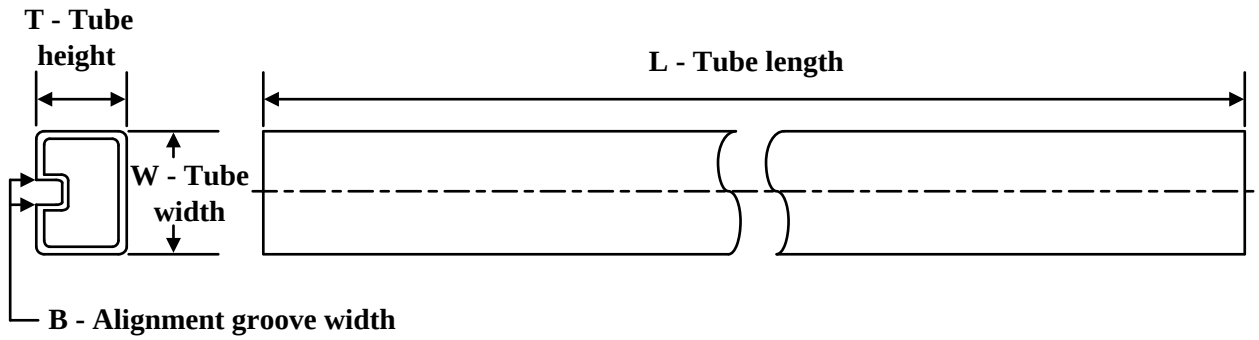
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

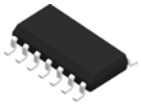
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS136DR	SOIC	D	14	2500	353.0	353.0	32.0
SN74LS136NSR	SOP	NS	14	2000	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74LS136N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS136N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS136N.A	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS136N.A	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS136NE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS136NE4	N	PDIP	14	25	506	13.97	11230	4.32

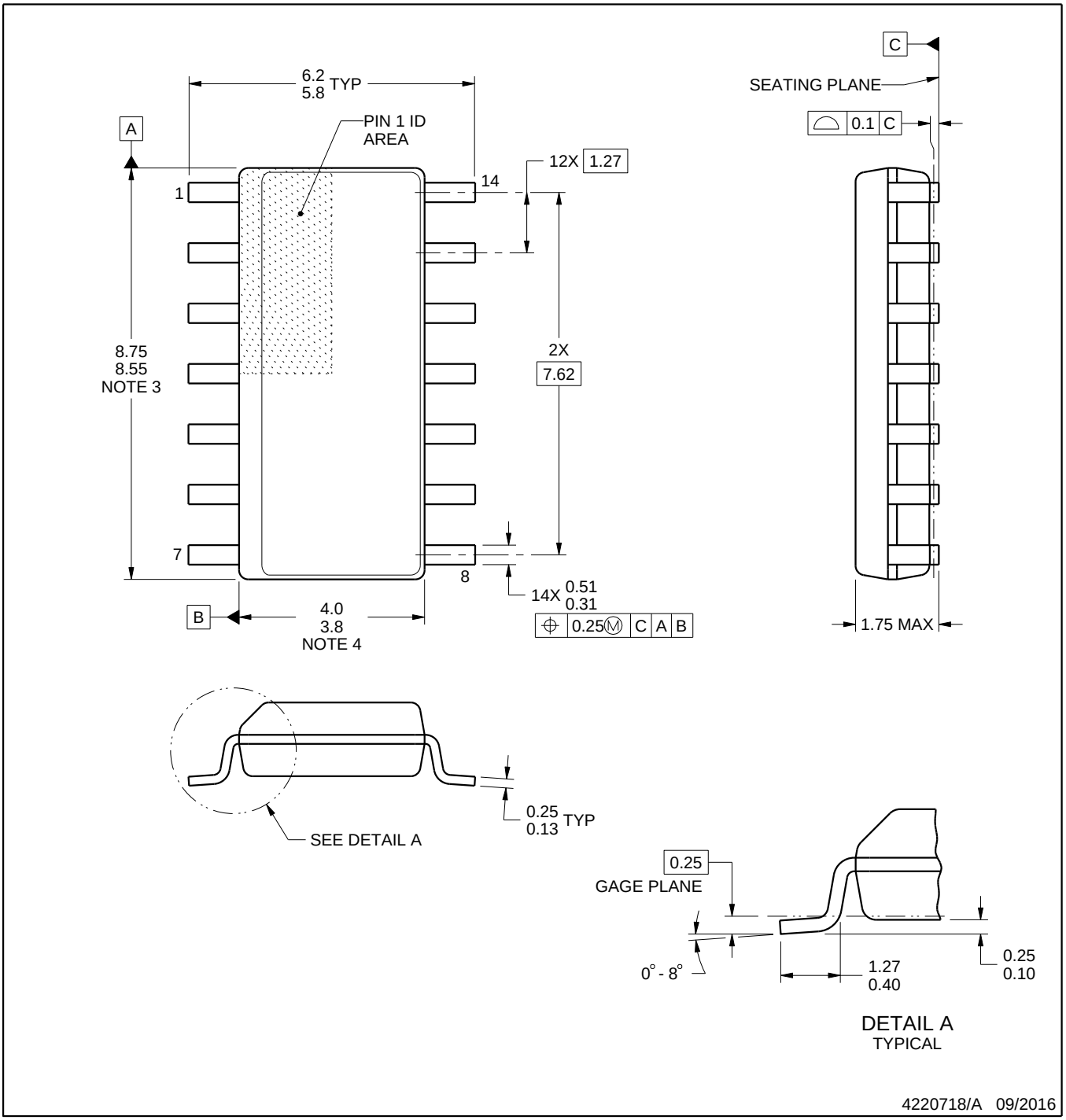


PACKAGE OUTLINE

D0014A

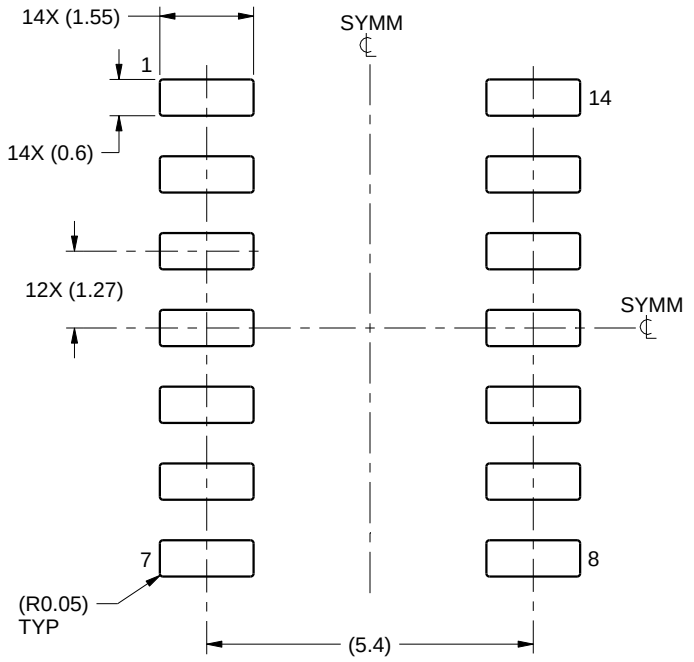
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

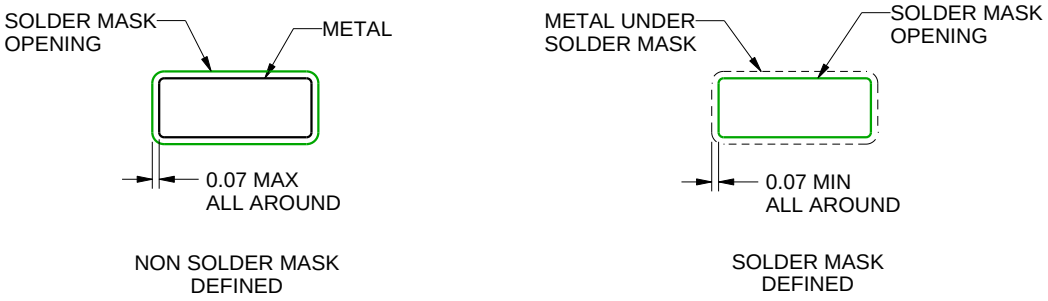


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

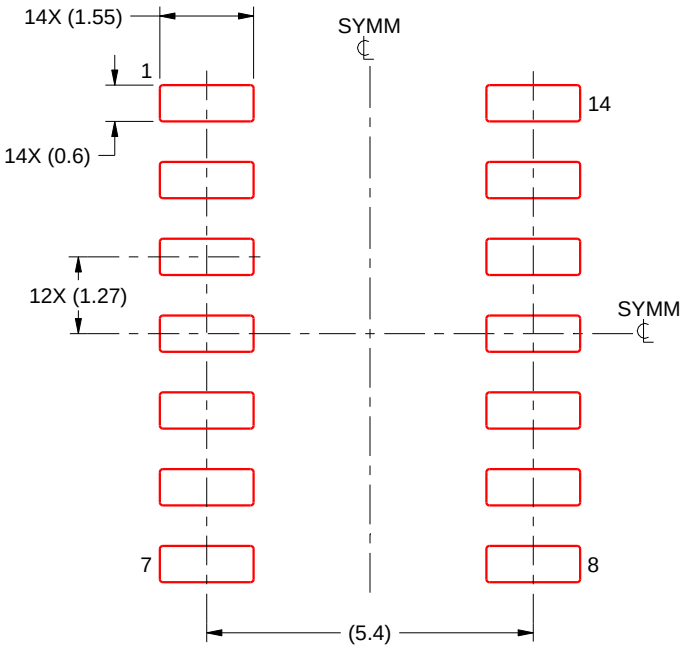
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

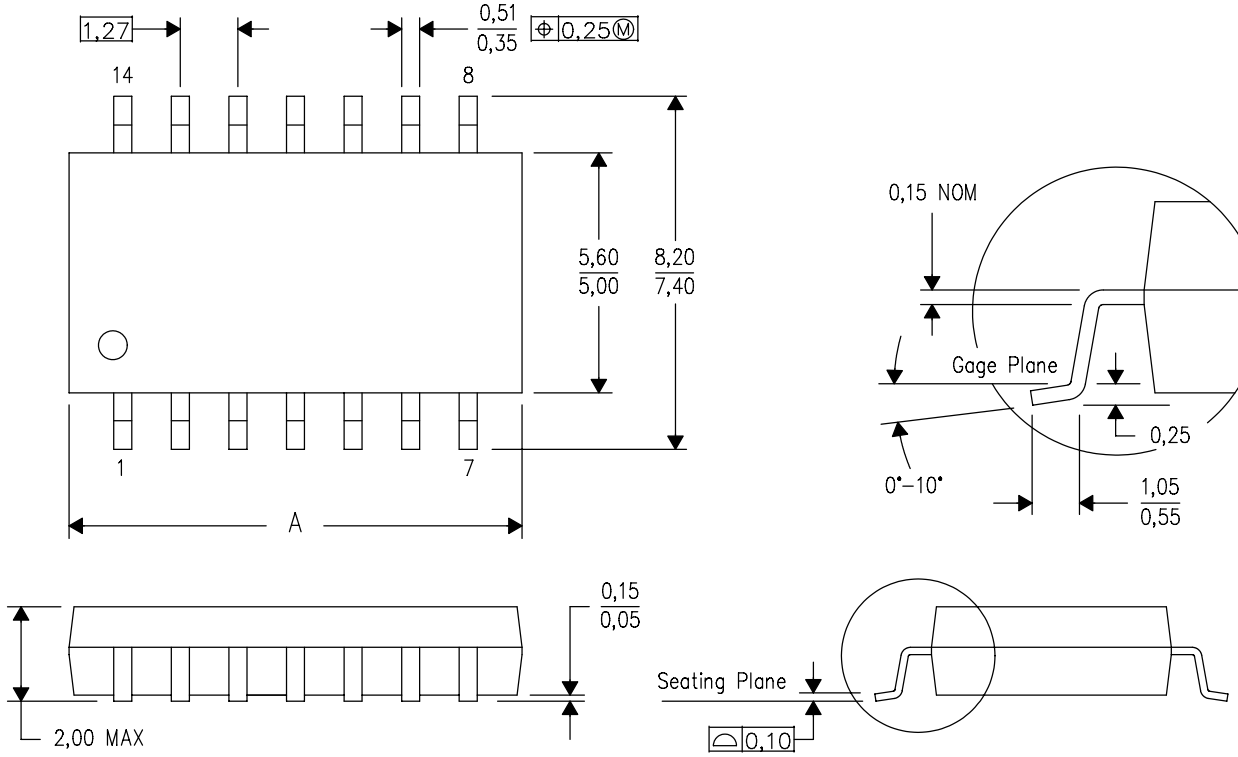
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

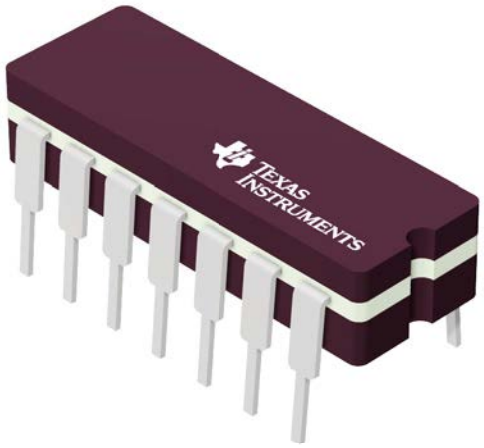
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

GENERIC PACKAGE VIEW

J 14 CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

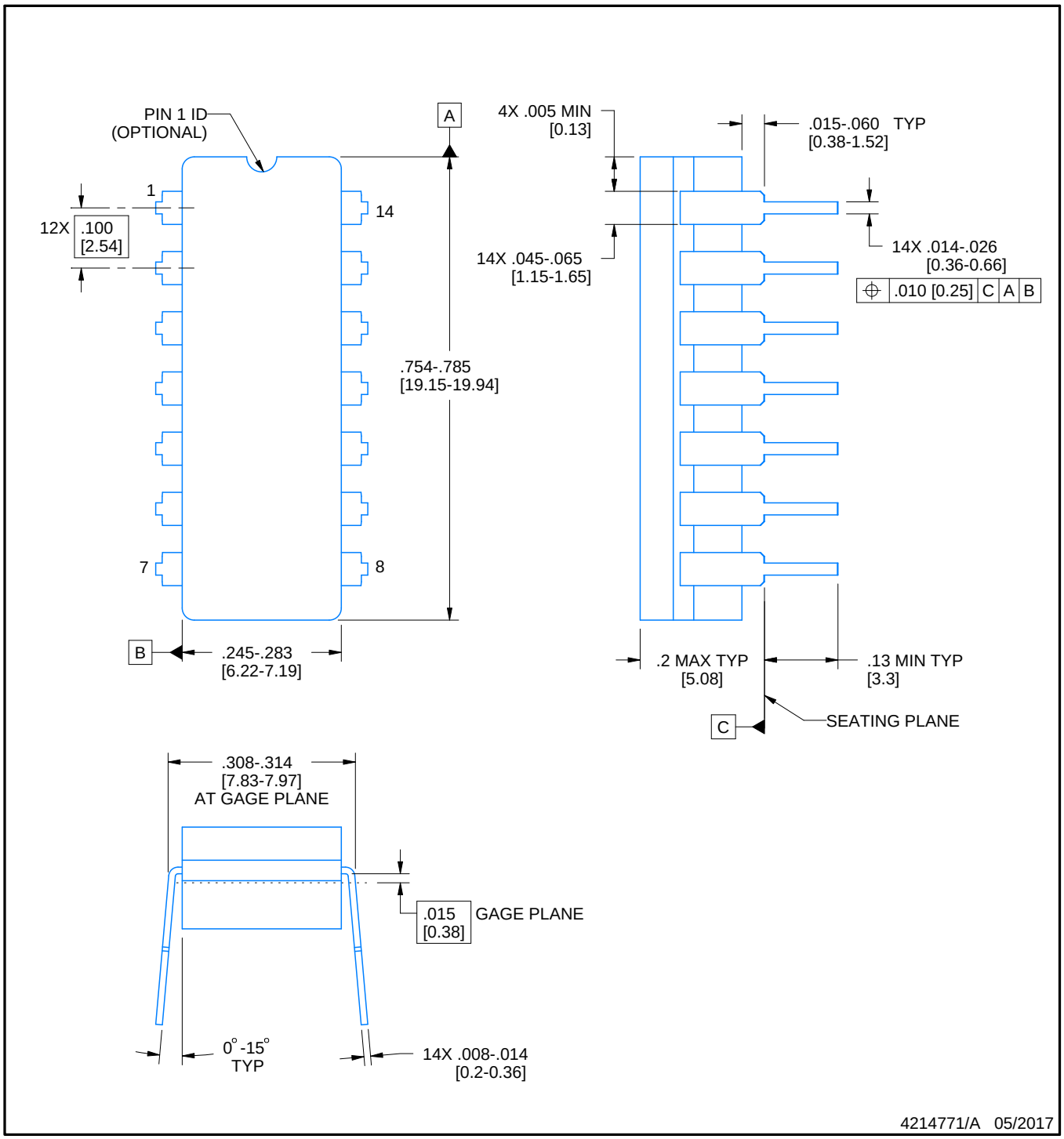
4040083-5/G

PACKAGE OUTLINE

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

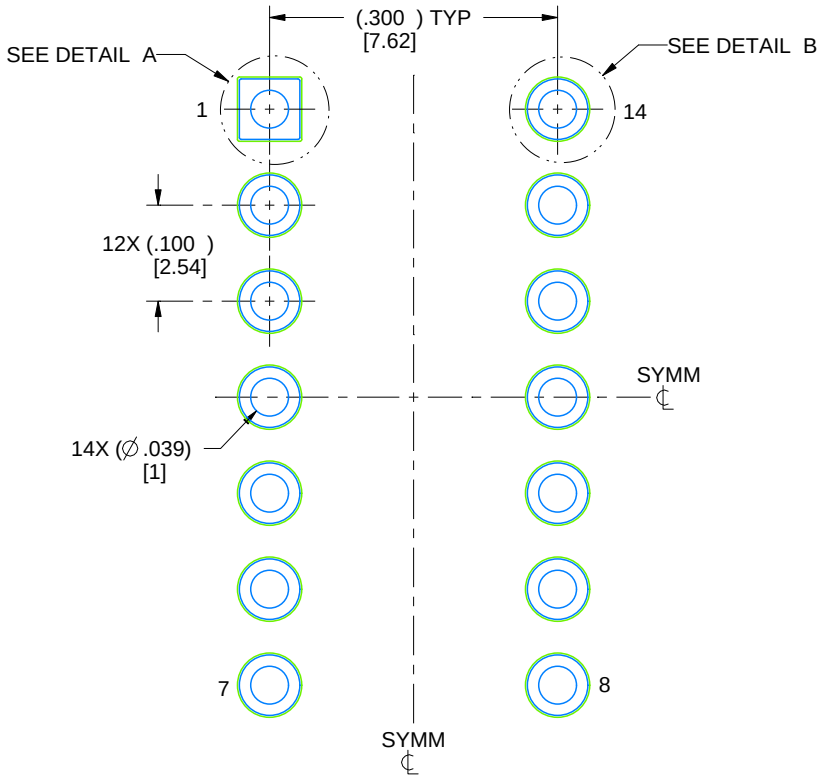
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermitically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

EXAMPLE BOARD LAYOUT

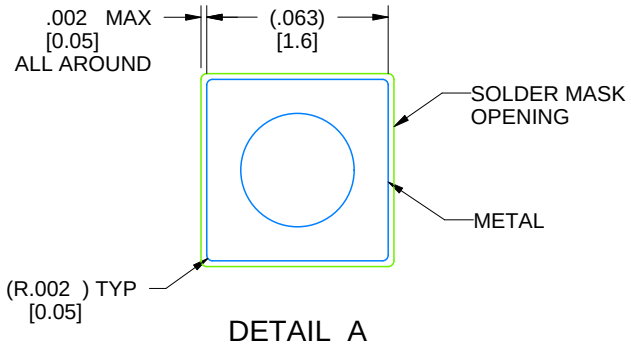
J0014A

CDIP - 5.08 mm max height

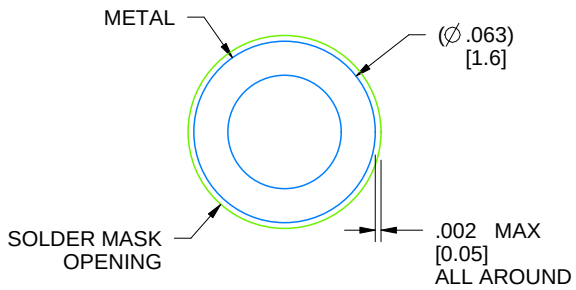
CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X



DETAIL A
SCALE: 15X



DETAIL B
13X, SCALE: 15X

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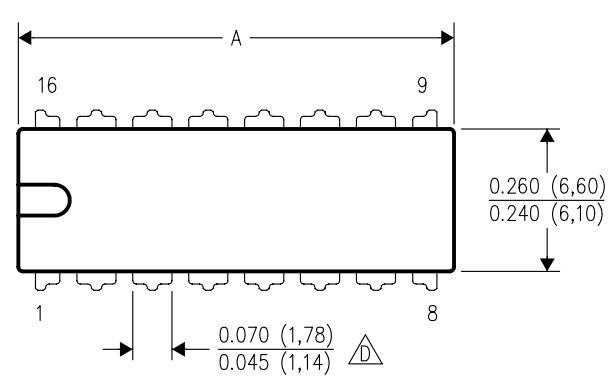
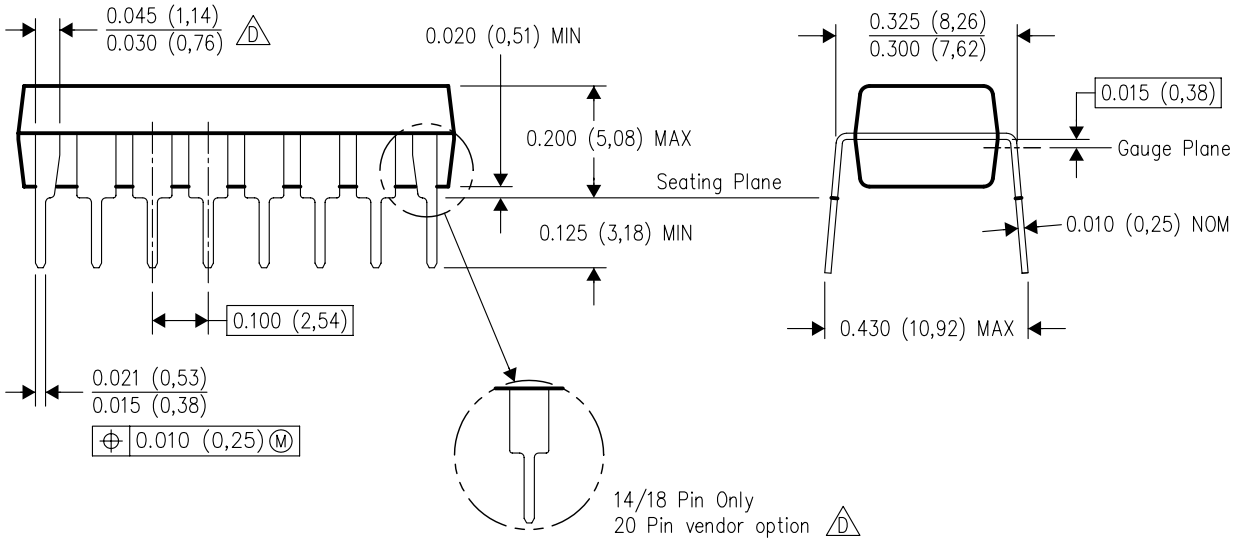
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



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NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265